



Eco-Friendly Technologies: Low-Cost and Low-Toxicity Thin Film Deposition

Guest Editor:

Dr. Valentina Belova

European Synchrotron Radiation
Facility (ESRF), 71 avenue des
Martyrs, 38000 Grenoble, France

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Message from the Guest Editor

Dear Colleagues,

Many measures have been already taken to reduce the use of hazardous materials in the processing as well as the production costs. Since the majority of the manufacturing steps in the electronics industry involve different kinds of thin-film deposition, there is a strong need for finding solutions to overcome the remaining health and environmental issues associated with thin-film technologies.

Here, we kindly invite authors to contribute to our new Special Issue, “Eco-Friendly Technologies: Low-Cost and Low-Toxicity Thin Film Deposition”, devoted to recent advances in the development of strategies for low-toxicity and/or low-energy processing being able to reduce raw material waste and emission of toxic agents during device manufacturing and after the disposal or abandonment. Research may cover (but is not limited to) any of the processing stages, such as formation of substrates, contacts, and interconnections; active layers in electronic devices (e.g., solar cells, FETs, LEDs, sensors); and other applications such as thin-film batteries and coatings.





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Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
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